

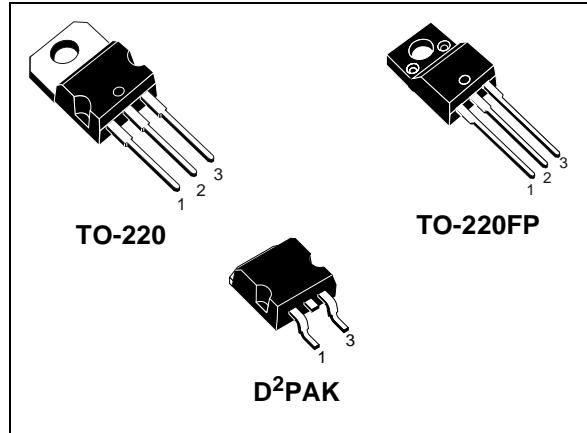


# STGP3NB60KD - STGP3NB60KDFP STGB3NB60KD

N-CHANNEL 6A - 600V - TO-220/TO-220FP/D<sup>2</sup>PAK  
SHORT CIRCUIT PROOF PowerMESH™ IGBT

TYPE	V <sub>CES</sub>	V <sub>CE(sat)</sub> (Max) @ 25°C	I <sub>c</sub> (#) @ 100°C
STGP3NB60KD	600 V	< 2.8 V	6 A
STGP3NB60KDFP	600 V	< 2.8 V	6 A
STGB3NB60KD	600 V	< 2.8 V	6 A

- HIGH INPUT IMPEDANCE (VOLTAGE DRIVEN)
- LOW ON-VOLTAGE DROP (V<sub>cesat</sub>)
- LOW GATE CHARGE
- HIGH CURRENT CAPABILITY
- OFF LOSSES INCLUDE TAIL CURRENT
- HIGH FREQUENCY OPERATION
- SHORT CIRCUIT RATED



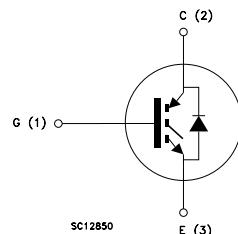
## DESCRIPTION

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH™ IGBTs, with outstanding performances. The suffix "K" identifies a family optimized for high frequency motor control applications with short circuit withstand capability.

## APPLICATIONS

- HIGH FREQUENCY MOTOR CONTROLS
- SMPS AND PFC IN BOTH HARD SWITCHING AND RESONANT TOPOLOGIES

## INTERNAL SCHEMATIC DIAGRAM



## ORDERING INFORMATION

SALES TYPE	MARKING	PACKAGE	PACKAGING
STGP3NB60KD	GP3NB60KD	TO-220	TUBE
STGP3NB60KDFP	GP3NB60KDFP	TO-220FP	TUBE
STGB3NB60KDT4	GB3NB60KD	D <sup>2</sup> PAK	TAPE & REEL

## STGP3NB60KD-STGP3NB60KDFP-STGB3NB60KD

### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		TO-220 D <sup>2</sup> PAK	TO-220FP	
$V_{CES}$	Collector-Emitter Voltage ( $V_{GS} = 0$ )	600		V
$V_{ECR}$	Emitter-Collector Voltage	20		V
$V_{GE}$	Gate-Emitter Voltage	$\pm 20$		V
$I_C$	Collector Current (continuous) at $T_C = 25^\circ\text{C}$ (#)	10		A
$I_C$	Collector Current (continuous) at $T_C = 100^\circ\text{C}$ (#)	6		A
$I_{CM}$ (■)	Collector Current (pulsed)	24		A
$P_{TOT}$	Total Dissipation at $T_C = 25^\circ\text{C}$	50	25	W
	Derating Factor	0.4	0.2	W/ $^\circ\text{C}$
$V_{ISO}$	Insulation Withstand Voltage A.C.	--	2500	V
$T_{stg}$	Storage Temperature	-55 to 150		$^\circ\text{C}$
$T_j$	Max. Operating Junction Temperature	150		$^\circ\text{C}$

(■) Pulse width limited by safe operating area

### THERMAL DATA

		TO-220 D <sup>2</sup> PAK	TO-220FP	
$R_{thj-case}$	Thermal Resistance Junction-case Max	2.5	5	$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal Resistance Junction-ambient Max	62.5		$^\circ\text{C}/\text{W}$

### ELECTRICAL CHARACTERISTICS (TCASE = 25 °C UNLESS OTHERWISE SPECIFIED) MAIN PARAMETERS

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{BR(CES)}$	Collector-Emitter Breakdown Voltage	$I_C = 250 \mu\text{A}, V_{GE} = 0$	600			V
$I_{CES}$	Collector cut-off ( $V_{GE} = 0$ )	$V_{CE} = \text{Max Rating}, T_C = 25^\circ\text{C}$ $V_{CE} = \text{Max Rating}, T_C = 125^\circ\text{C}$			50 500	$\mu\text{A}$ $\mu\text{A}$
$I_{GES}$	Gate-Emitter Leakage Current ( $V_{CE} = 0$ )	$V_{GE} = \pm 20\text{V}, V_{CE} = 0$			$\pm 100$	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{CE} = V_{GE}, I_C = 250\mu\text{A}$	5		7	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE} = 15\text{V}, I_C = 3 \text{ A}$ $V_{GE} = 15\text{V}, I_C = 3 \text{ A}, T_j = 125^\circ\text{C}$		2.3 1.9	2.8	V

**SWITCHING PARAMETERS**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{fs}$ (1)	Forward Transconductance	$V_{CE} = 25V, I_C = 3 A$		2.4		S
$C_{ies}$ $C_{oes}$ $C_{res}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{CE} = 25V, f = 1 MHz, V_{GE} = 0$		220 50 5.8		pF pF pF
$Q_g$ $Q_{ge}$ $Q_{gc}$	Total Gate Charge Gate-Emitter Charge Gate-Collector Charge	$V_{CE} = 480V, I_C = 3 A,$ $V_{GE} = 15V$		14 3.3 7.5	18	nC nC nC
$t_{scw}$	Short Circuit Withstand Time	$V_{ce} = 0.5 V_{BR(CES)}, V_{GE}=15V,$ $T_j = 125^\circ C, R_G = 10 \Omega$	10			μs
$t_{d(on)}$ $t_r$	Turn-on Delay Time Rise Time	$V_{CC} = 480 V, I_C = 3 A$ $R_G = 10\Omega, V_{GE} = 15 V$		14 5		ns ns
$(di/dt)_{on}$ $E_{on}$	Turn-on Current Slope Turn-on Switching Losses	$V_{CC}= 480 V, I_C = 3 A R_G=10\Omega$ $V_{GE} = 15 V, T_j = 125^\circ C$		520 30		A/μs μJ
$t_c$ $t_r(V_{off})$ $t_d(off)$ $t_f$ $E_{off(**)}$ $E_{ts}$	Cross-over Time Off Voltage Rise Time Delay Time Fall Time Turn-off Switching Loss Total Switching Loss	$V_{cc} = 480 V, I_C = 3 A,$ $R_{GE} = 10 \Omega , V_{GE} = 15 V$ $T_j = 25 ^\circ C$		90 20 33 100 58 85		ns ns ns ns μJ μJ
$t_c$ $t_r(V_{off})$ $t_d(off)$ $t_f$ $E_{off(**)}$ $E_{ts}$	Cross-over Time Off Voltage Rise Time Delay Time Fall Time Turn-off Switching Loss Total Switching Loss	$V_{cc} = 480 V, I_C = 3 A,$ $R_{GE} = 10 \Omega , V_{GE} = 15 V$ $T_j = 125 ^\circ C$		190 54 90 130 111 195		ns ns ns ns μJ μJ

**COLLECTOR-EMITTER DIODE**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_f$ $I_{fm}$	Forward Current Forward Current Pulsed				3 24	A A
$V_f$	Forward On-Voltage	$I_f = 1.5 A$ $I_f = 1.5 A, T_j = 125 ^\circ C$		1.2 0.95	1.8	V V
$t_{rr}$ $Q_{rr}$ $I_{rrm}$	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_f = 3 A, V_R = 35 V,$ $T_j = 125^\circ C, di/dt = 100A/\mu s$		45 70 2.7		ns nC A

Note: 1. Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %.

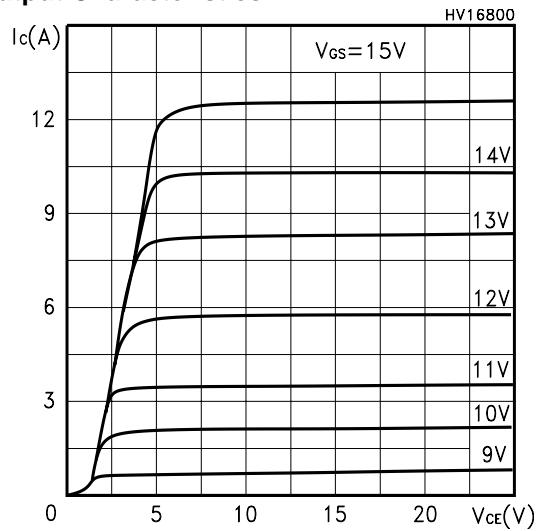
(\*\*)Losses include Also the Tail (Jedec Standardization)

(#) Calculated according to the iterative formula:

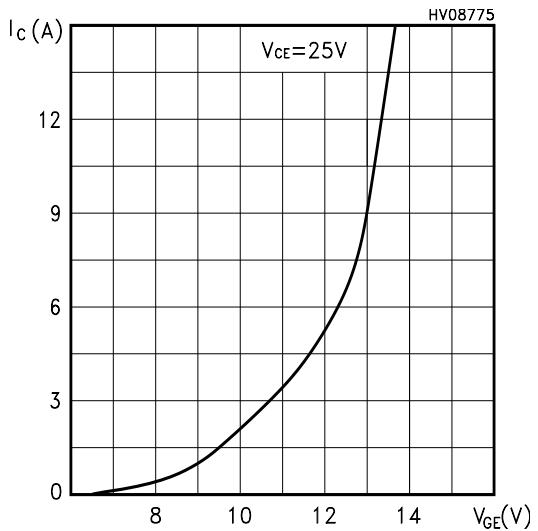
$$I_C(T_C) = \frac{T_{JMAX} - T_C}{R_{THJ-C} \times V_{CESAT(MAX)}(T_C, I_C)}$$

## STGP3NB60KD-STGP3NB60KDFP-STGB3NB60KD

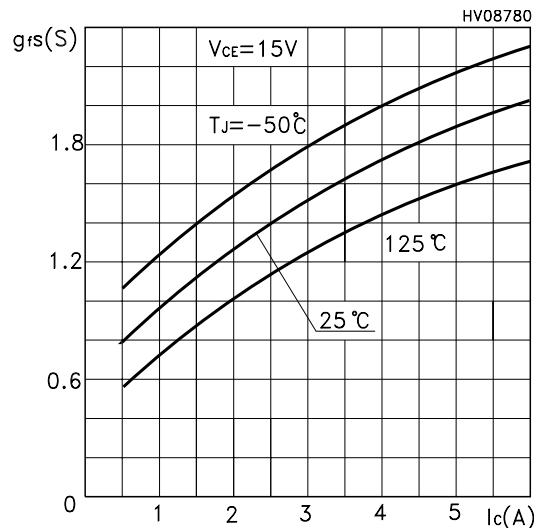
### Output Characteristics



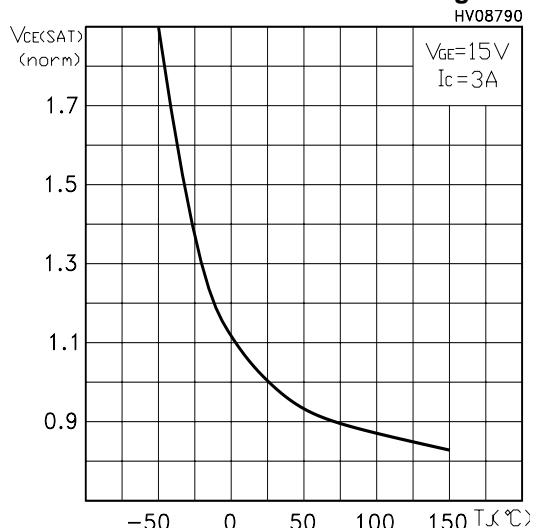
### Transfer Characteristics



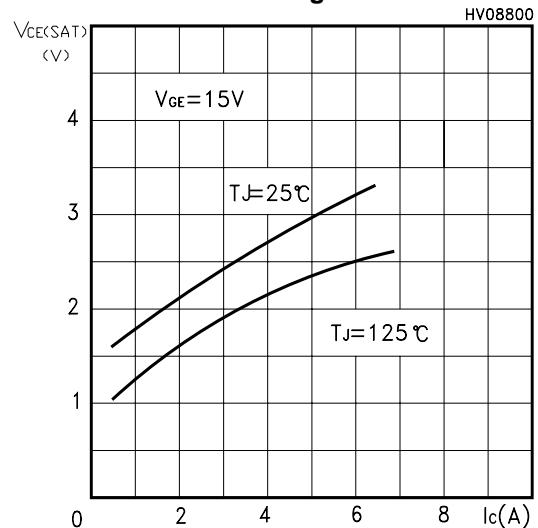
### Transconductance



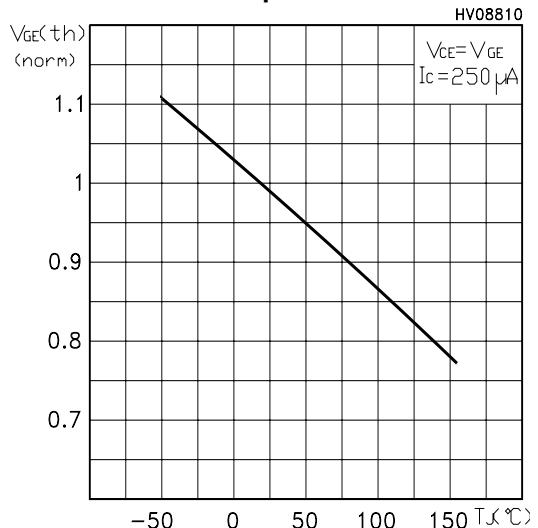
### Normalized Collector-Emitter On Voltage vs Temp.



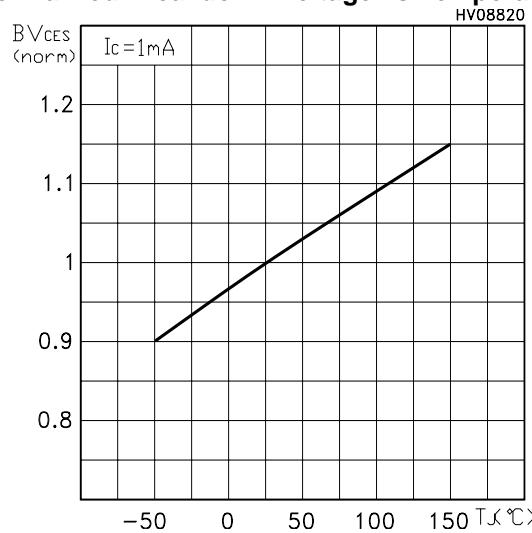
### Collector-Emitter On Voltage vs Collector Current



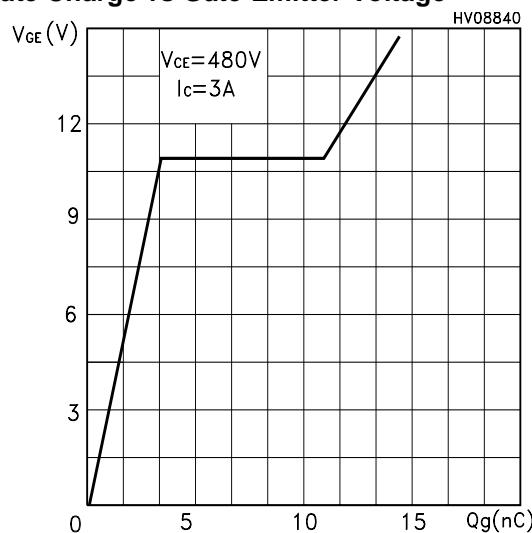
### Gate Threshold vs Temperature



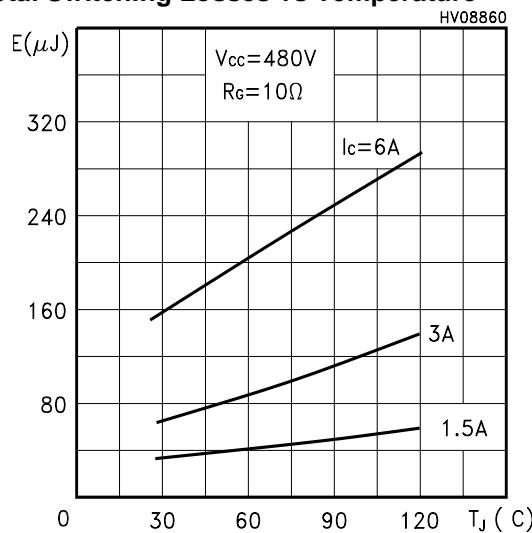
**Normalized Breakdown Voltage vs Temperature**



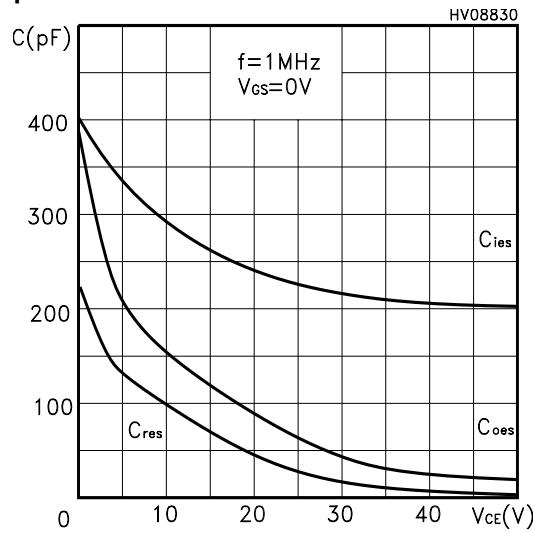
**Gate Charge vs Gate-Emitter Voltage**



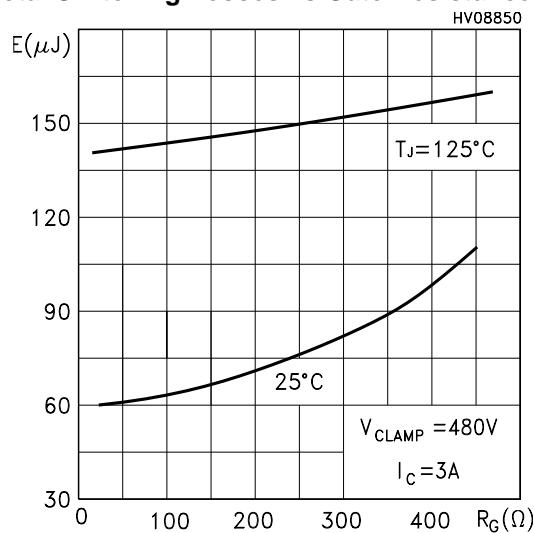
**Total Switching Losses vs Temperature**



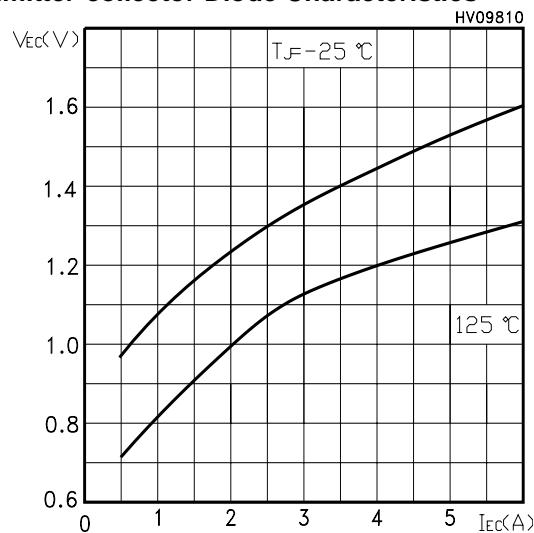
**Capacitance Variations**



**Total Switching Losses vs Gate Resistance**

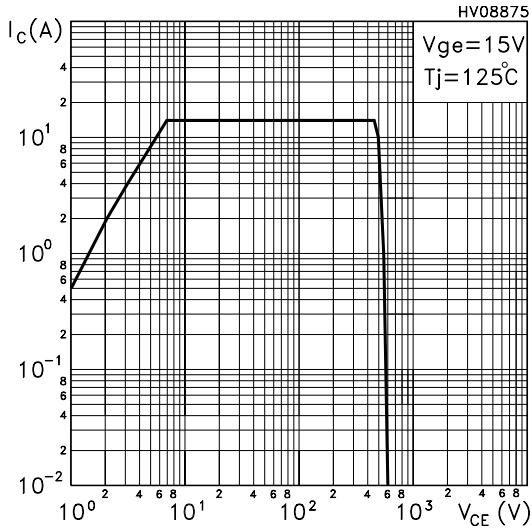


**Emitter-collector Diode Characteristics**

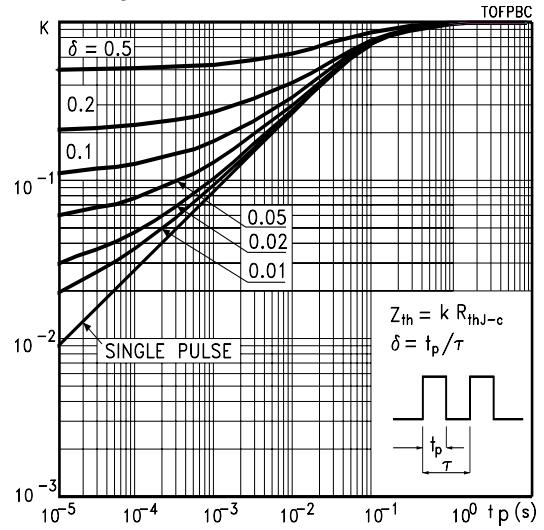


## STGP3NB60KD-STGP3NB60KDFP-STGB3NB60KD

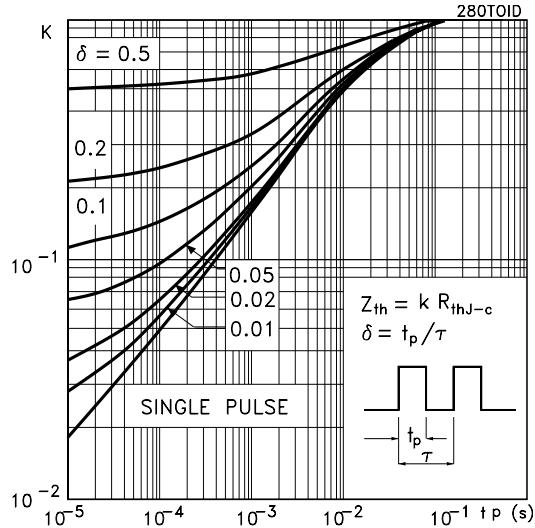
### Turn-Off SOA



### Thermal Impedance for TO-220FP

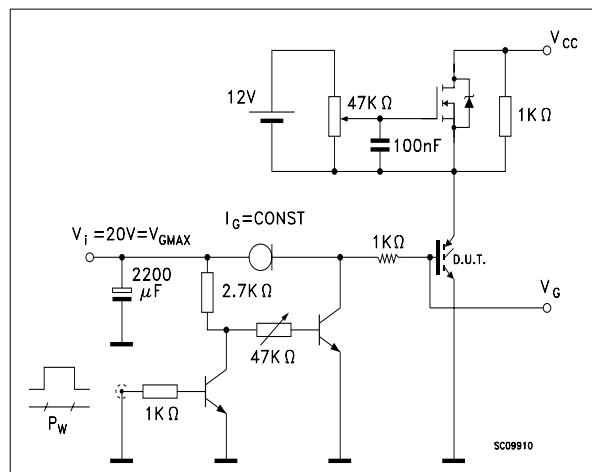


### Thermal Impedance for TO-220 / D2PAK

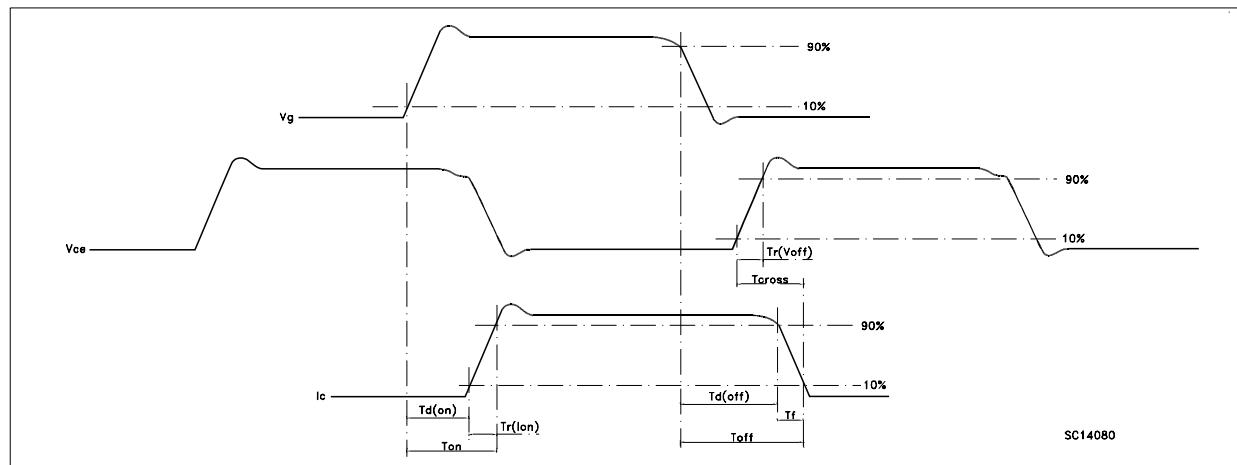
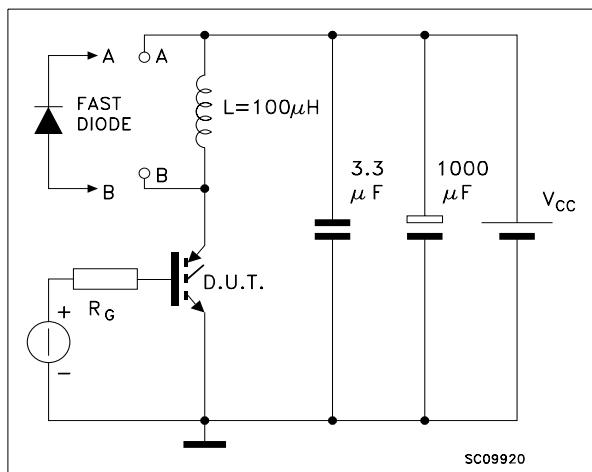


## STGP3NB60KD-STGP3NB60KDFP-STGB3NB60KD

**Fig. 1: Gate Charge test Circuit**



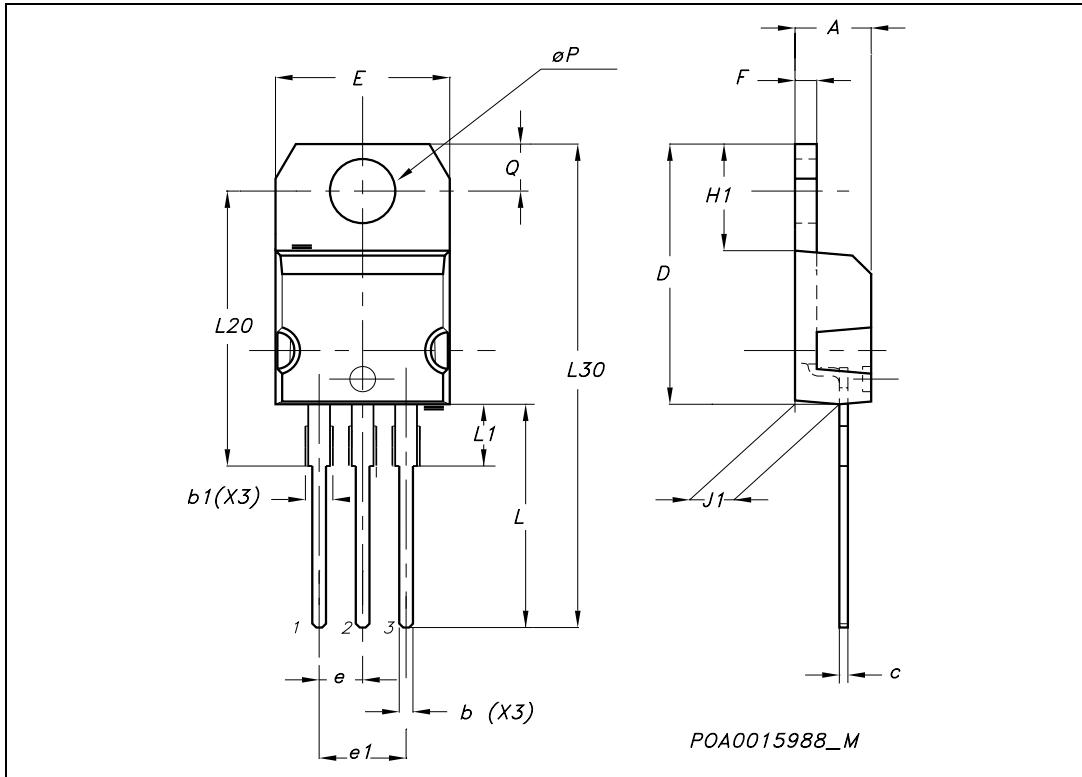
**Fig. 2: Test Circuit For Inductive Load Switching**



## STGP3NB60KD-STGP3NB60KDFP-STGB3NB60KD

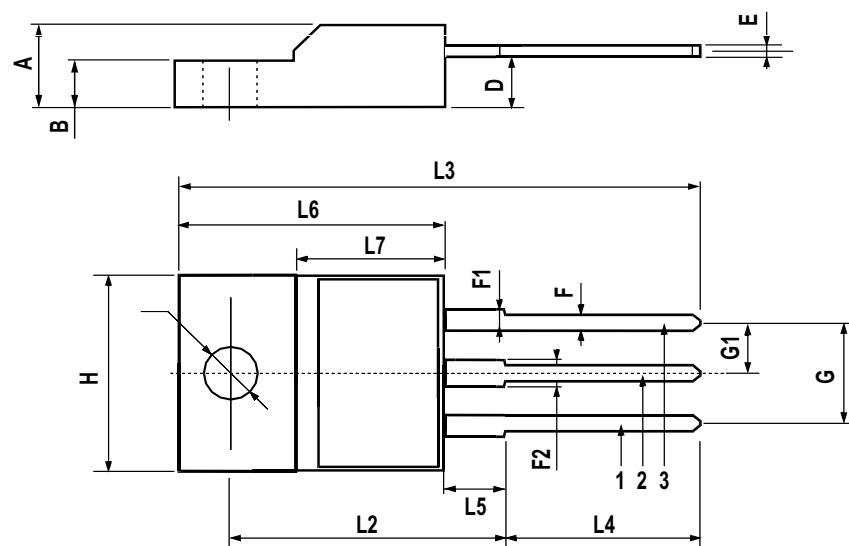
### TO-220 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
$\phi P$	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



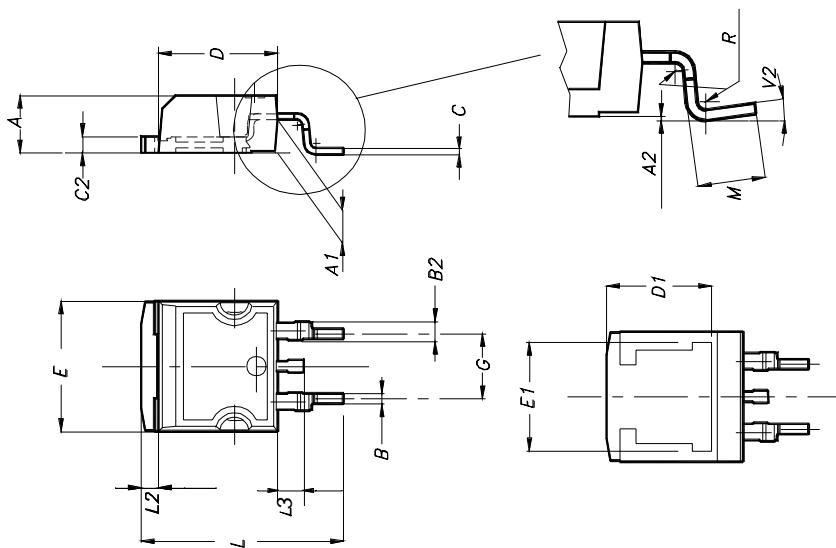
**TO-220FP MECHANICAL DATA**

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
H	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	.0385		0.417
L5	2.9		3.6	0.114		0.141
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126

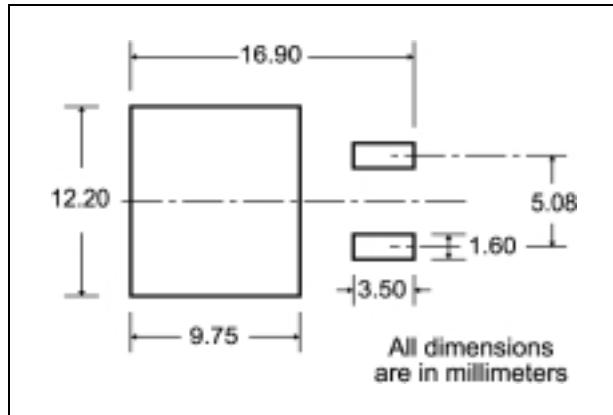


**D<sup>2</sup>PAK MECHANICAL DATA**

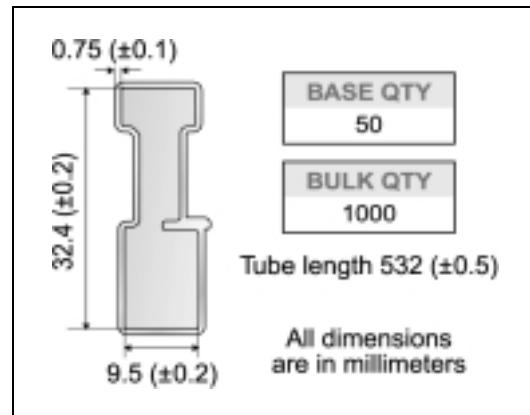
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
C	0.45		0.6	0.017		0.023
C2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1		8			0.315	
E	10		10.4	0.393		
E1		8.5			0.334	
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.625
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068
M	2.4		3.2	0.094		0.126
R		0.4			0.015	
V2	0°		8°			



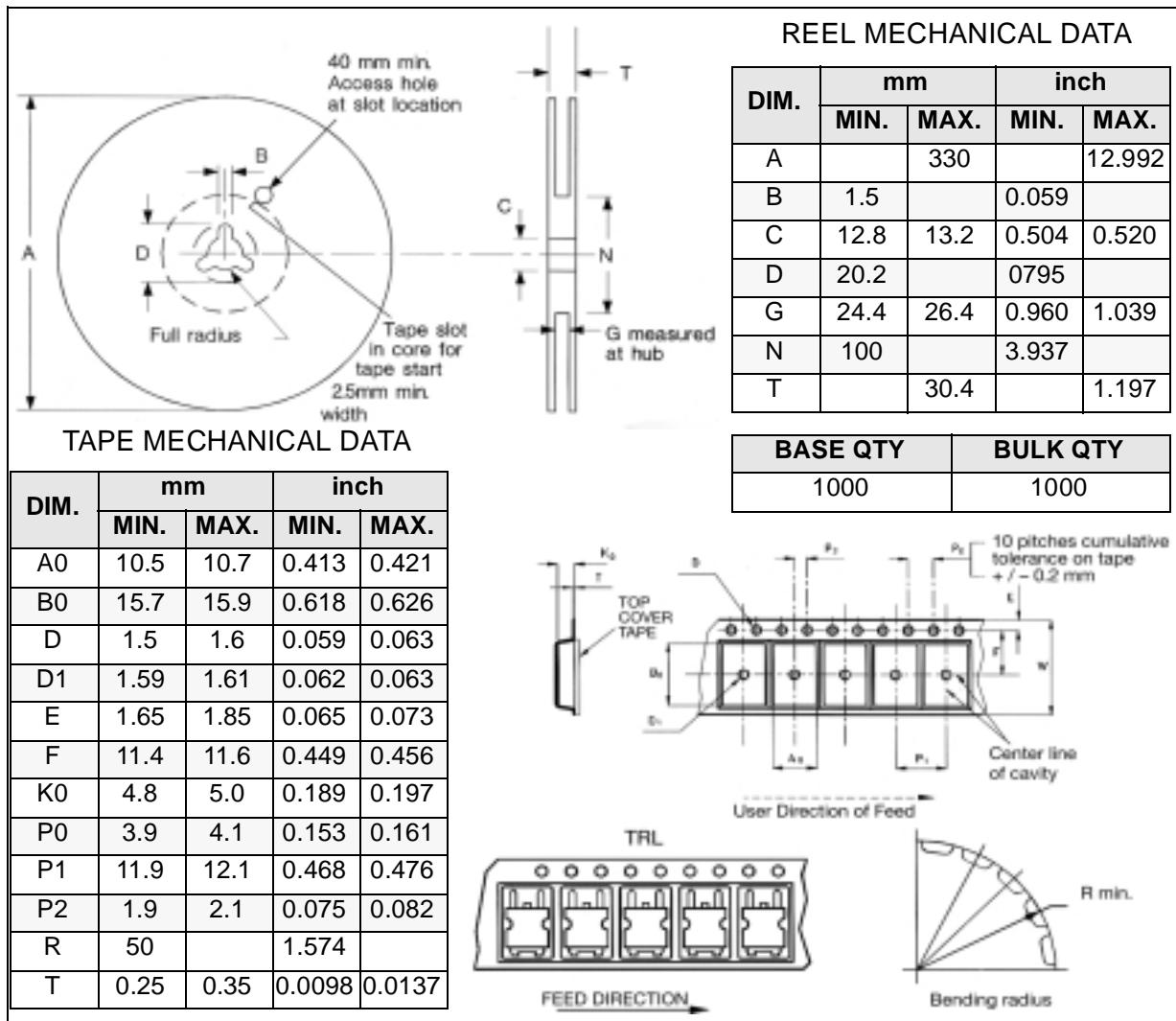
**D<sup>2</sup>PAK FOOTPRINT**



**TUBE SHIPMENT (no suffix)\***



**TAPE AND REEL SHIPMENT (suffix "T4")\***



\* on sales type

## **STGP3NB60KD-STGP3NB60KDFP-STGB3NB60KD**

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